



Part No.: U3535C2VGB20

Product picture



Product introduction

This series of deep uv packaging products are specially designed for applications with high radiation power and directivity requirements. The surface of the packaging body in the form of a patch device, and the use of special uv glass, so as to optimize the product life and performance. It can be used in plant lighting, fluorescence analyzer, medical testing, food and pharmaceutical processing, sterilization and other fields.

Features

- ✧ Ceramic packaging
- ✧ Standard SMD process
- ✧ In line with the ROHS standard

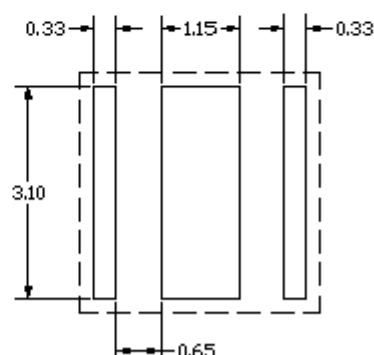
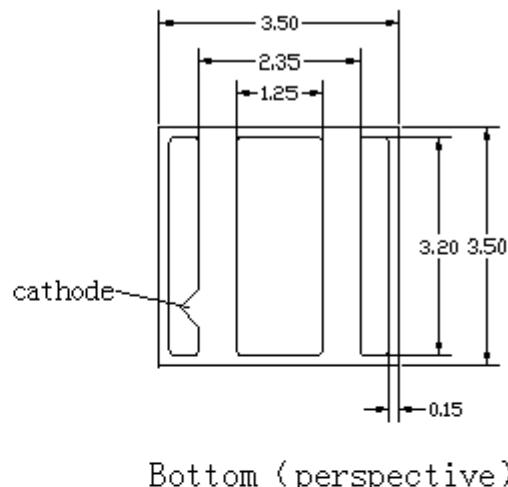
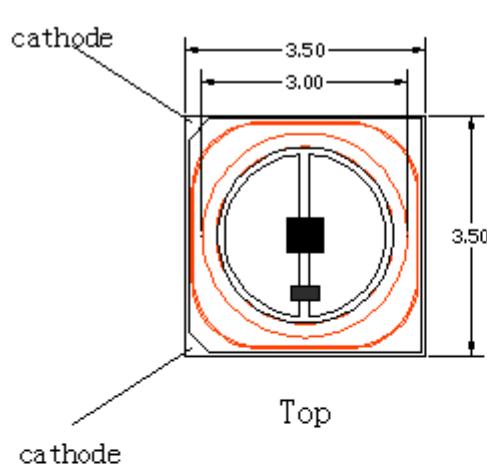
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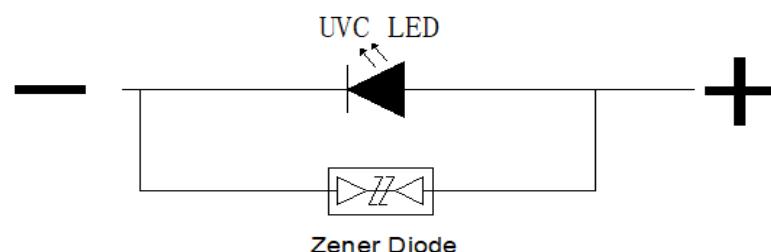


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Outline dimensions: (Unit: mm, The tolerance $\pm 0.1\text{mm}$)



Recommended Mask Size





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Photoelectric properties (Ta = 25°C)

Parameter	Forward current	Symbol	Min.	Typ	Max	Unit
The peak wavelength	If=60mA	λp	270	275	280	nm
Output Radiated power		P _{opt}	--	8	--	mW
Forward Voltage		Vf	5	5.5	6.5	V
FWHM		Δ λ	--	9	--	nm
Viewing Angle		2θ _{1/2}	--	120	--	°
Thermal resistance (T _j -T _{sp})		R _{th}	--	27	--	°C/W
Output Radiated power	If=120mA	P _{opt}	--	15	--	mW

Instructions: T_c = 25°C; The tolerance of Forward voltage: ±0.1V; The tolerance of Radiation flux: ±8%; The tolerance of peak wavelength : ±3nm.

Limit service condition :

Parameter	Symbol	Unit	Range
Forward current	If	mA	≤120
Junction temperature	T _j	°C	≤90
Working temperature	T _{opr}	°C	-30-60
The welding conditions	T _{sol}	-	260°C < 5seconds



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Photoelectric parameter curve :

Fig.1 Relative Radiant Power VS Forward Current

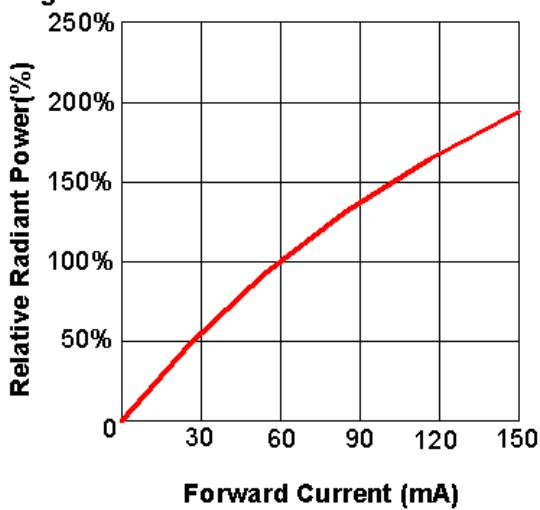


Fig.2 Forward Current VS Forward Voltage ($T_a=25^{\circ}\text{C}$)

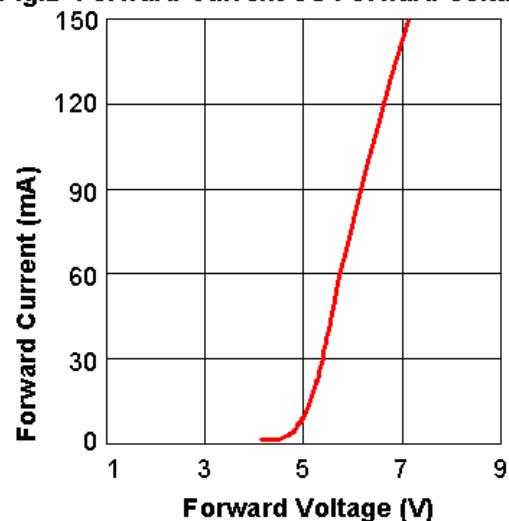


Fig.3 Forward Voltage VS Ambient Temperature

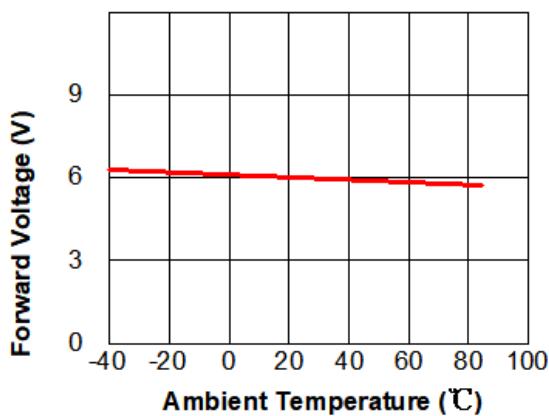
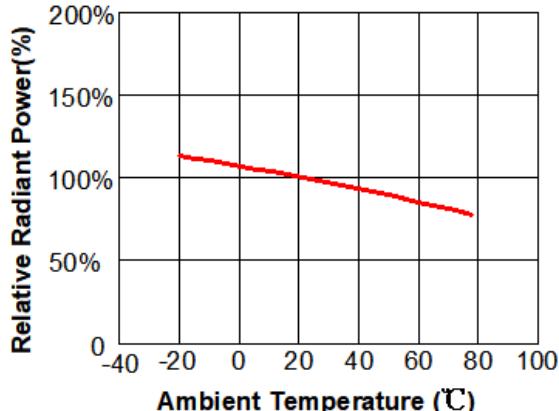


Fig.4 Relative Radiant Power VS Ambient Temperature





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Fig.5 Peak Wavelength VS Forward Current

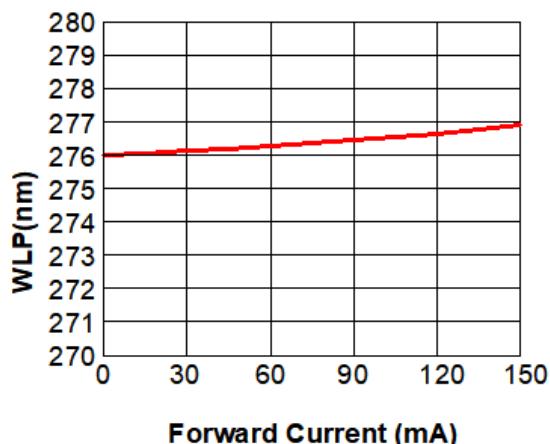


Fig.6 Forward Current VS Ambient Temperature

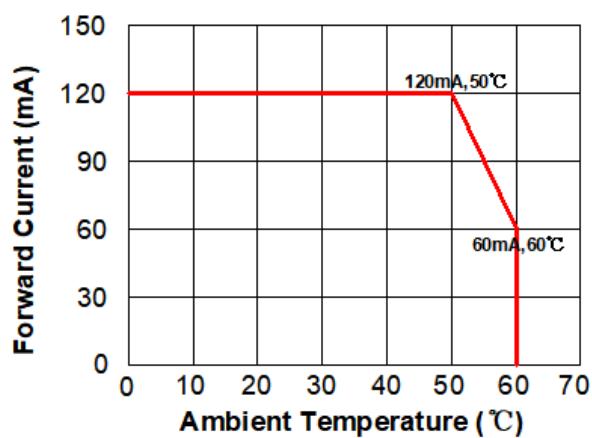


Fig.7 Relative Intensity VS WLP

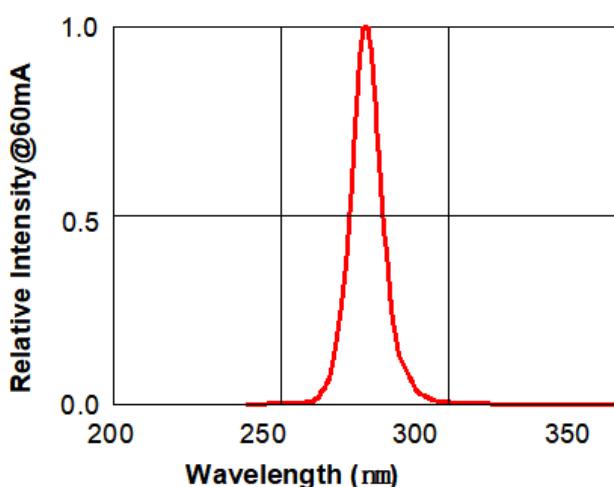
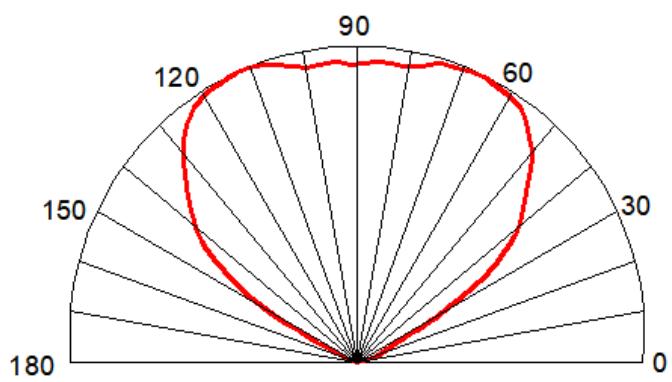


Fig.8 Radiation pattern@60mA





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Reliability test

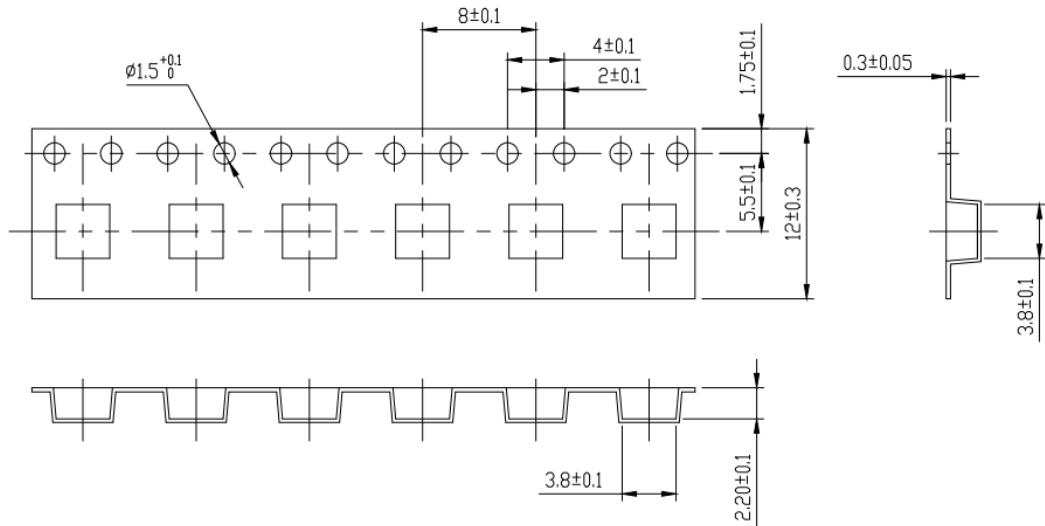
Test	Test Conditions	Failure Criterion
Normal temperature life test	25°C, 60mA, 1000Hours	Forward voltage, $V_f > 110\%$ Radiation power, $P_{opt} < 70\%$
High temperature storage	100°C, 1000Hours	
Low temperature storage	-40°C, 1000Hours	
Temperature cycle (100times)	-40°C (30mins) ~ +25°C (5mins) +100°C(30mins) ~ +25°C (5mins)	

Notice:

Test the device at room temperature

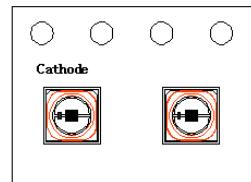
Packing

(Unit: mm)

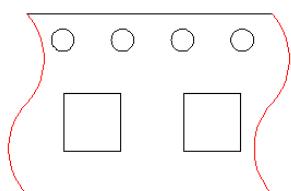




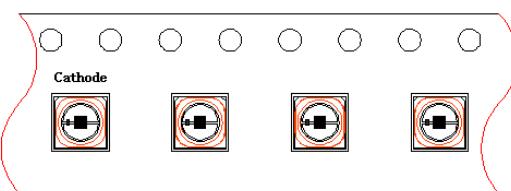
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The End

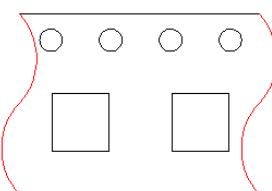


The blank space With 200mm

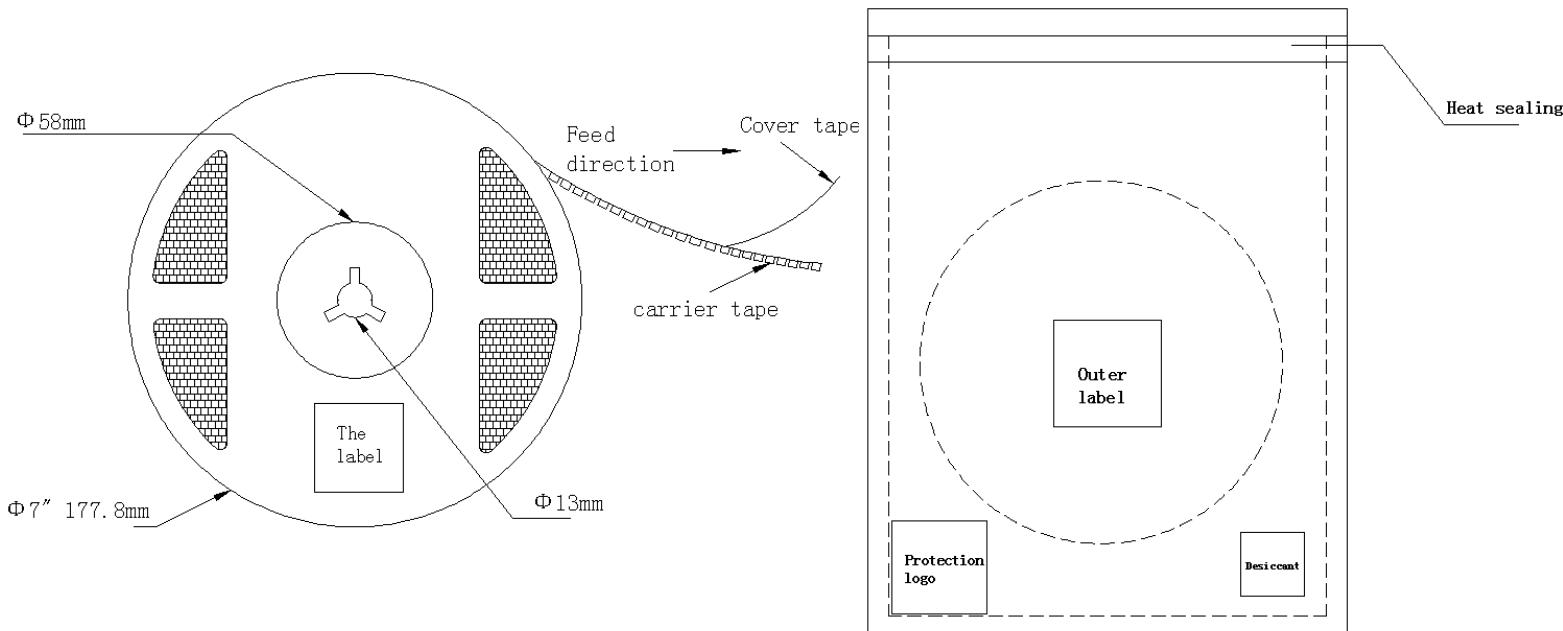


A roll of 1000PCS

Feed Direction



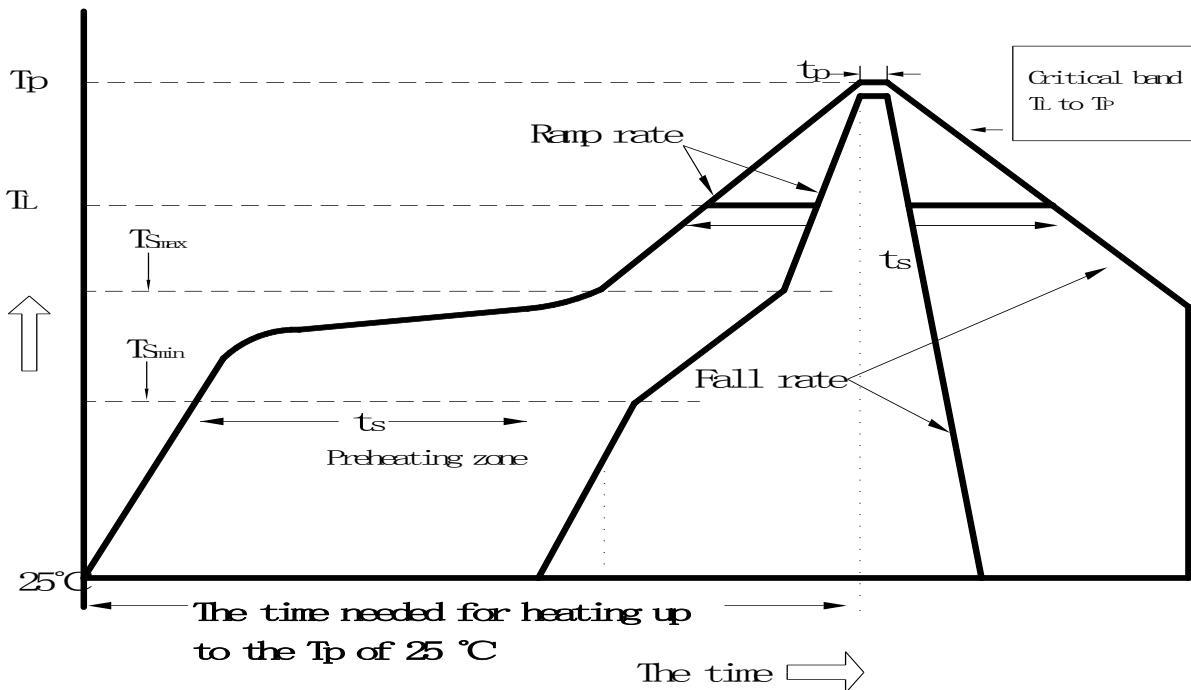
The blank space With 400mm





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Recommend suitable temperature curve formula



Temperature curve characteristics	Lead-free solder
Ramp rate (Tsmax to TP)	Max 3°C/S
Preheat: minimum temperature (Tsmin)	150°C
Preheat: maximum temperature (Tsmax)	200°C
Maintain a higher temperature: temperature (TL)	60-180 S
Liquid temperature (TL)	217°C
Maintain a higher temperature: time (TL)	60-150 S
Tp/temperature	260°C
Specify the time within 5°C of the actual peak temperature	20-40 S
The slope rate (Tp to TL)	Max 6°C/S
The time needed for heating up to the Tp of 25 °C	Max 8 min